



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21B473KBCNNWC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 47 nF, 50V, ±10%, X7R, 0805

## A. Samsung Part Number

<u>CL</u> <u>21</u> <u>B</u> <u>473</u> <u>K</u> <u>B</u> <u>C</u> <u>N</u> <u>N</u> <u>W</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor								
2	Size	0805 (inch co	ode) L	: 2.0	± 0.1	mm	W:	1.25	± 0.1	mm
3	Dielectric	X7R		8	Inner e	lectrode		Ni		
4	Capacitance	<b>47</b> nF			Termin	ation		Cu		
⑤	Capacitance	±10 %			Plating			Sn 100	0%	(Pb Free)
	tolerance			9	Produc	:t		Norma	al	
6	Rated Voltage	50 V		10	Special	I		Produ	ct for N	letwork application
7	Thickness	0.85 ± 0.1	mm	11)	Packag	jing		Cardb	oard T	ype,7"reel(4,000ea)

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition						
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms						
Tan δ (DF)	0.025 max.							
Insulation	More than 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance								
Appearance	No abnormal exterior appearance	Visual inspection						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X7R							
Characteristics	(From -55 ℃ to 125 ℃, Capacitance change should be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	Tan δ, IR : initial spec.							

	Performance	Test condition					
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm					
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)					
		2hours × 3 direction (x, y, z)					
Moisture	Capacitance change: within ±12.5%	With rated voltage					
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0 hours					
	IR : More than 25MΩ· <i>μ</i> F						
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage					
Resistance	Tan δ : 0.05 max	Max. operating temperature					
	IR : More than 50MΩ·μF						
		1000+48/-0 hours					
Temperature	Capacitance change: within ±7.5%	1 cycle condition					
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C					
		→ Max. operating temperature → 25°C					
		5 cycles test					

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.